

#### P-Channel 30-V (D-S) MOSFET

## **General Description**

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low RDS(on)and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers,PCMCIA cards, cellular and cordless telephones.

## **Features**

- Advanced high cell density Trench technology
- Fast switching speed
- Lower On-resistance
- 100% EAS Guaranteed
- Simple Drive Requirement

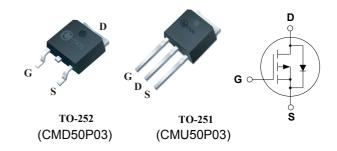
## **Product Summary**

BVDSS	RDSON	ID
-30V	12mΩ	-50A

## **Applications**

- DC-DC Converters
- Desktop PCs
- LED controller

## TO-252/251 Pin Configuration



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units		
$V_{DS}$	Drain-Source Voltage	-30	V		
$V_{GS}$	Gate-Source Voltage	±20	V		
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current	Continuous Drain Current -50			
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current -25		Α		
I <sub>DM</sub>	Pulsed Drain Current <sup>1</sup> -150		А		
EAS	Single Pulse Avalanche Energy	115	mJ		
I <sub>AS</sub>	Single Pulse Avalanche Current -50		Α		
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation 60		W		
T <sub>STG</sub>	Storage Temperature Range -55 to 175		°C		
$T_J$	Operating Junction Temperature Range	-55 to 175	°C		

## **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>θJA</sub>	Junction-to-Ambient <sup>2</sup>		50	
$R_{ heta JC}$	Junction-to-Case (Drain)		1.1	°C/W

# CMD50P03/CMU50P03



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## Electrical Characteristics ( $T_J$ =25 $\,^{\circ}$ C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-30			V
D	Static Drain-Source On-Resistance <sup>1</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A			12	mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-15A			18	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250uA$	-1		-3	V
L	Drain-Source Leakage Current	$V_{DS}$ =-30V, $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			-1	uA
I <sub>DSS</sub>		V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V , T <sub>J</sub> =125 ℃			-50	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-15V, I <sub>D</sub> =-20A		52		S
Qg	Total Gate Charge	V <sub>DS</sub> =-24V, I <sub>D</sub> =-50A V <sub>GS</sub> =0 to -10V		45		
Q <sub>gs</sub>	Gate-Source Charge			6.5		nC
$Q_{gd}$	Gate-Drain Charge			10		
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ =-15V, $V_{GS}$ =-10V, $R_{G}$ =3.5 $\Omega$ $I_{D}$ =-50A		11		
Tr	Rise Time			9		
T <sub>d(off)</sub>	Turn-Off Delay Time			54		ns
T <sub>f</sub>	Fall Time			20		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-25V, V <sub>GS</sub> =0V , f=1MHz		3900		
Coss	Output Capacitance			750		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			500		

## **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	−V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-50	Α
I <sub>SM</sub>	Pulsed Source Current <sup>1</sup>				-150	Α
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>F</sub> =-30A			-1.5	V

## Notes

- 1. Pulse test; pulse width≤ 300µs, duty cycle≤ 2%.
- 2. When mounted on 1" square PCB (FR-4 material).

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